

KYOCERA KE-1100A-S3

Epoxy; Epoxide

KYOCERA Chemical Corporation

Message:

Molding Compounds for Area Array Packages (BGA, CSP etc.)

Special Epoxy Molding Compounds Optimizing Warpage and Applicable to Fine Pitch Wire for BGA Package

Strong Points

Less Warpage in All Types of Area Array Packages due to High Tg Characteristic.

Applicable to Fine Pitch Wire Bonding with Good Wire Sweep Performance.

Achieve High Yield after Molding due to Excellent Moldability that allows its application to MAP.

Application

Standard P-BGA, HS-BGA and LGA Package.

Multi Chip Module (Stacked or Side by Side Layout)

IC Card, Memory Card etc.

Low Alpha Ray Type: KE-2100A-S3

General Information		
Features	Good Moldability	
Uses	Electrical/Electronic Applications	
Physical	Nominal Value	Unit
Specific Gravity	1.90	g/cm ³
Spiral Flow	190	cm
Solution Viscosity	6000	mPa · s
Mechanical	Nominal Value	Unit
Flexural Modulus	15000	MPa
Flexural Strength	130	MPa
Thermal	Nominal Value	Unit
Glass Transition Temperature	200	°C
CLTE - Flow		
-- 1	1.4E-5	cm/cm/°C
-- 2	4.9E-5	cm/cm/°C
NOTE		
1.	Alpha 1	
2.	Alpha 2	

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